DC BUS_P

DC BUS_M

DC Link Current

R Y B

+0V DC input

MOTOR

TIDA-00201

TPS7A4700

5V

REF5025

+ OPA322

2V5

TLV70033

3V3

REF2025

2V5_REF

1V25_REF

All 3 phase Fluxgate sensor outputs are summed together and given as inputs to these comparators.

Optimal SPI Connection for External Motor Controller

Delfino™

F2837x

ADS7854

THS4531

VTH

VTL

TLC372

Overcurrent Indication

Earth Fault Indication

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2014

Sanjay Pithadia

Designed for:
Public Release

Assembly Variant:
001

Project Title:
DE I/P ADC Signal Conditioning For Fluxgate Sensor

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Not in version control

SVN Rev:
TIDA-00201
Number: Rev: E2
The circuit diagram shows two sections: CH1 OVERCURRENT FAULT DETECTION and CH2 OVERCURRENT FAULT DETECTION. Each section contains resistors, capacitors, and transistors, indicating the electrical connections and signal flow. The diagram is labeled with component values and symbols, such as resistors (R1, R2, etc.), capacitors (C1, C2, etc.), and transistors (U1, U2, etc.).

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TWO ADS7854s FOR INTERFACING WITH EXTERNAL MOTOR CONTROLLER

GROUND FAULT DETECTION

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PCB Label

ZZ1

These assemblies are ESD sensitive. ESD precautions shall be observed.

ZZ2

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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